|  |  |  |  |  |  |  |  |  |  |
| --- | --- | --- | --- | --- | --- | --- | --- | --- | --- |
| 型号代号 | ${modelCode} | 单机名称 | ${productName} | 单板名称 | ${singleBoardName} | 图纸代号 | ${drawingCode} | 阶段 | ${stage} |

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| --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- | --- |
| ${isInheritArr0} | 继承分机名称 | | ${inheritExtensionName} | | 单板名称 | ${inheritSingleBoardName} | | | 图纸代号 | ${inheritDrawingCode} | 阶段 | ${inheritStage} |
| **（只能对同阶段或更高阶段产品继承，单板经过型号验证且完全继承，无任何修改，只需填到4之前）** | | | | | | | | | | | | |
| ${isInheritArr1} | ${newSingleBoardNoteArr0} | | | | | | | ${newSingleBoardNoteArr1} | | | | | |
| 单板特性  （第二轮设计必填） | 继承单板图纸是否归档受控 | | | ${isOnFile0} | | | ${isOnFile1} | | | | | | |
| 继承单板三单是否闭环 | | | ${isClosedLoop0} | | | ${isClosedLoop1} | | | | | | |
| 相对于继承单板有无变化 | | | ${changeSection0} | | | ${changeSection1} | | | | | | |
| 变化内容 | ${changeContent} | | | | | | | | | | | |
| 变化原因 | ${changeReason} | | | | | | | | | | | |

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| 填写说明：设计、校对、审核需要对表内所有项目进行检查；填表时不能用符号代替“正确/错误”或“是/否” |

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| **检查项目** | **设计检查结果及说明** | **校对检查结果** | **审核检查结果** |
| **状态** | | | |
| 1. ${checkDemand0} | ${firstCheck0} | ${secondCheck0} | ${thirdCheck0} |
| **电路的原理图** | | | |
| 2. ${checkDemand1} | ${firstCheck1} | ${secondCheck1} | ${thirdCheck1} |
| **电路的接口** | | | |
| 3. ${checkDemand2} | ${firstCheck2} | ${secondCheck2} | ${thirdCheck2} |
| 4. ${checkDemand3} | ${firstCheck3} | ${secondCheck3} | ${thirdCheck3} |
| **版图** | | | |
| 5. ${checkDemand4} | ${firstCheck4} | ${secondCheck4} | ${thirdCheck4} |
| **器件的使用** | | | |
| 6. ${checkDemand5} | ${firstCheck5} | ${secondCheck5} | ${thirdCheck5} |
| 7. ${checkDemand6} | ${firstCheck6} | ${secondCheck6} | ${thirdCheck6} |
| 8. ${checkDemand7} | ${firstCheck7} | ${secondCheck7} | ${thirdCheck7} |
| 9. ${checkDemand8} | ${firstCheck8} | ${secondCheck8} | ${thirdCheck8} |
| 10. ${checkDemand9} | ${firstCheck9} | ${secondCheck9} | ${thirdCheck9} |
| 11. ${checkDemand10} | ${firstCheck10} | ${secondCheck10} | ${thirdCheck10} |
| 12. ${checkDemand11} | ${firstCheck11} | ${secondCheck11} | ${thirdCheck11} |
| 13. ${checkDemand12} | ${firstCheck12} | ${secondCheck12} | ${thirdCheck12} |
| 14. ${checkDemand13} | ${firstCheck13} | ${secondCheck13} | ${thirdCheck13} |
| 15. ${checkDemand14} | ${firstCheck14} | ${secondCheck14} | ${thirdCheck14} |
| 16. ${checkDemand15} | ${firstCheck15} | ${secondCheck15} | ${thirdCheck15} |
| 17. ${checkDemand16} | ${firstCheck16} | ${secondCheck16} | ${thirdCheck16} |
| 18. ${checkDemand17} | ${firstCheck17} | ${secondCheck17} | ${thirdCheck17} |
| 19. ${checkDemand18} | ${firstCheck18} | ${secondCheck18} | ${thirdCheck18} |
| **微带片的设计** | | | |
| 20. ${checkDemand19} | ${firstCheck19} | ${secondCheck19} | ${thirdCheck19} |
| 21. ${checkDemand20} | ${firstCheck20} | ${secondCheck20} | ${thirdCheck20} |
| 22. ${checkDemand21} | ${firstCheck21} | ${secondCheck21} | ${thirdCheck21} |
| 23. ${checkDemand22} | ${firstCheck22} | ${secondCheck22} | ${thirdCheck22} |
| 24. ${checkDemand23} | ${firstCheck23} | ${secondCheck23} | ${thirdCheck23} |
| **基片打孔** | | | |
| 25. ${checkDemand24} | ${firstCheck24} | ${secondCheck24} | ${thirdCheck24} |
| 26. ${checkDemand25} | ${firstCheck25} | ${secondCheck25} | ${thirdCheck25} |
| 27. ${checkDemand26} | ${firstCheck26} | ${secondCheck26} | ${thirdCheck26} |
| **腔体尺寸** | | | |
| 28. ${checkDemand27} | ${firstCheck27} | ${secondCheck27} | ${thirdCheck27} |

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| 单板设计师/日期: | ${submitInfo0} | 校 对/日期: | ${submitInfo1} |
| 审 核/日期: | ${submitInfo2} | 批 准/日期: | ${submitInfo3} |